

ABSTRACT

An adhesive composition contains a compound having no siloxane bond and having a linear or branched alkyl chain having 5 or more carbon atoms, in which the adhesive composition is a curable adhesive composition used for forming an adhesive layer of a laminate including a semiconductor substrate or an electronic device layer, a support substrate, and the adhesive layer provided between the semiconductor substrate or the electronic device layer and the support substrate.

FIG. 1